AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (cancelled)

2. **(currently amended)** A method of marking wafer-level chip scale packages, the method comprising the steps of:

providing a wafer having a plurality of dice formed thereon, wherein the dice have been packaged into a plurality of semi-finished chip scale packages, wherein each of the semi-finished chip scale packages comprises a plurality of terminals for making external electrical connections, each die has a plurality of bonding pads on an active surface thereof, the bonding pads are electrically connected to the respective terminals, and a backside surface of each die is exposed from a surface of the respective semi-finished chip scale package;

positioning the semi-finished chip scale packages formed on the wafer;

printing ink marks by transferring ink from a printing device onto the exposed backside surfaces of the dice with the printing device being brought into contact with the dice;

after said printing, curing the ink marks on the dice; and

dicing the wafer to obtain a plurality of separated chip scale packages.

3. (previously presented) The method as claimed in claim 2, further comprising the step of removing defective ink marks after the printing step and before the curing step.

4. (previously presented) The method as claimed in claim 2, wherein the

positioning step is performed by a positioning device, the positioning device and the printing device are positioned on two opposing sides of the wafer, and the printing step is performed by coaxially aligning the printing device with the positioning device.

5. (previously presented) The method as claimed in claim 2, wherein the wafer has a plurality of dicing streets between the semi-finished chip scale packages, and the positioning step is performed by finding the dicing street with a charge coupled device (CCD).

6. (previously presented) The method as claimed in claim 5, wherein the positioning step is performed by a positioning device, the positioning device and the printing device are positioned on two opposing sides of the wafer, and the printing step is performed by coaxially aligning the printing device with the positioning device.

7-8. (cancelled)

9. (previously presented) The method as claimed in claim 2, wherein the printing step is performed by printing the backside surfaces of all of the dice in one action.

10. (previously presented) The method as claimed in claim 2, wherein all of the semi-finished chip scale packages are positioned simultaneously.

11. **(cancelled)**

12. (previously presented) The method as claimed in claim 2, wherein the printing step comprising the step of applying ink in a recognizable pattern directly on the exposed backside surface surfaces of the dice to form said ink marks.

13. (previously presented) The method as claimed in claim 2, wherein the

printing step comprising the step of applying ink in a recognizable pattern indicative of an identifier of each said die directly on the exposed backside surface of the die.